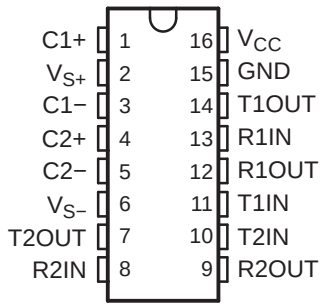
DUAL RS-232 DRIVER/RECEIVER WITH IEC61000-4-2 PROTECTION

FEATURES

- **Meets or Exceeds TIA/RS-232-F and ITU Recommendation V.28**
- **Operates From a Single 5-V Power Supply With 1.0-μF Charge-Pump Capacitors**
- **Operates up to 120 kbit/s**
- **Two Drivers and Two Receivers**
- **±30-V Input Levels**
- **Low Supply Current . . . 8 mA Typical**
- **ESD Protection Exceeds JESD22**
  - **2000-V Human-Body Model (HBM) (A114-A)**
- **Upgrade With Improved ESD (15-kV HBM) and 0.1-μF Charge-Pump Capacitors Is Available With the TRS202**

D, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



APPLICATIONS

- **TIA/RS-232-F**
- **Battery-Powered Systems**
- **Terminals**
- **Modems**
- **Computers**

DESCRIPTION/ORDERING INFORMATION

The TRS232 is a dual driver/receiver that includes a capacitive voltage generator to supply TIA/RS-232-F voltage levels from a single 5-V supply. Each receiver converts TIA/RS-232-F inputs to 5-V TTL/CMOS levels. This receiver has a typical threshold of 1.3 V, a typical hysteresis of 0.5 V, and can accept ±30-V inputs. Each driver converts TTL/CMOS input levels into TIA/RS-232-F levels. The driver, receiver, and voltage-generator functions are available as cells in the Texas Instruments LinASIC™ library.

ORDERING INFORMATION

T_A	PACKAGE(1)(2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube of 25	TRS232CN	TRS232CN
	SOIC – D	Tube of 40	TRS232CD	TRS232C
		Reel of 2500	TRS232CDR	
	SOIC – DW	Tube of 40	TRS232CDW	TRS232C
		Reel of 2000	TRS232CDWR	
	SOP – NS	Reel of 2000	TRS232CNSR	TRS232C
	TSSOP – PW	Tube of 25	TRS232CPW	TRS232C
		Reel of 2000	TRS232CPWR	
–40°C to 85°C	PDIP – N	Tube of 25	TRS232IN	TRS232IN
	SOIC – D	Tube of 40	TRS232ID	TRS232I
		Reel of 2500	TRS232IDR	
	SOIC – DW	Tube of 40	TRS232IDW	TRS232I
		Reel of 2000	TRS232IDWR	
	SOP – NS	Reel of 2000	TRS232INSR	TRS232I
	TSSOP – PW	Tube of 25	TRS232IPW	TRS232I
		Reel of 2000	TRS232IPWR	

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

FUNCTION TABLES

Each Driver(1)

INPUT TnIN	OUTPUT TnOUT
L	H
H	L

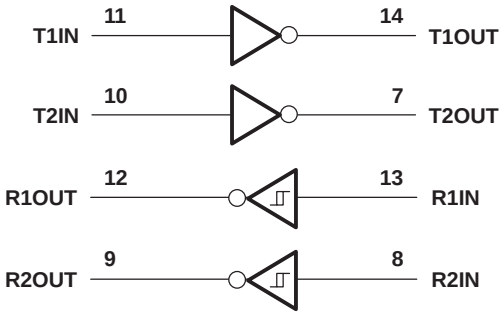
(1) H = high level, L = low level

Each Receiver(1)

INPUT RnIN	OUTPUT RnOUT
L	H
H	L

(1) H = high level, L = low level

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Input supply voltage range(2)		–0.3	6	V
V_{S+}	Positive-output supply voltage range		V_{CC} – 0.3	15	V
$V_{S–}$	Negative-output supply voltage range		–0.3	–15	V
V_I	Input voltage range	Driver	–0.3	V_{CC} + 0.3	V
		Receiver		±30	
V_O	Output voltage range	T1OUT, T2OUT	$V_{S–}$ – 0.3	V_{S+} + 0.3	V
		R1OUT, R2OUT	–0.3	V_{CC} + 0.3	
	Short-circuit duration	T1OUT, T2OUT		Unlimited	
θ_{JA}	Package thermal impedance(3)(4)	D package		73	°C/W
		DW package		57	
		N package		67	
		NS package		64	
		PW package		108	
T_J	Operating virtual junction temperature			150	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to network GND.
(3) Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage	T1IN, T2IN	2			V
V_{IL}	Low-level input voltage	T1IN, T2IN			0.8	V
	Receiver input voltage	R1IN, R2IN			±30	V
T_A	Operating free-air temperature	TRS232C	0		70	°C
		TRS232I	–40		85	

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 4)

PARAMETER		TEST CONDITIONS	MIN	TYP(2)	MAX	UNIT
I_{CC}	Supply current	V_{CC} = 5.5 V, All outputs open, T_A = 25°C		8	10	mA

(1) Test conditions are C1–C4 = 1 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 5 V and T_A = 25°C.

DRIVER SECTION

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature range

PARAMETER			TEST CONDITIONS		MIN	TYP(2)	MAX	UNIT
V_{OH}	High-level output voltage	T1OUT, T2OUT	R_L = 3 kΩ to GND		5	7		V
V_{OL}	Low-level output voltage(3)	T1OUT, T2OUT	R_L = 3 kΩ to GND			–7	–5	V
r_o	Output resistance	T1OUT, T2OUT	V_{S+} = V_{S-} = 0,	V_O = ±2 V	300			Ω
I_{OS}(4)	Short-circuit output current	T1OUT, T2OUT	V_{CC} = 5.5 V,	V_O = 0		±10		mA
I_{IS}	Short-circuit input current	T1IN, T2IN	V_I = 0				200	µA

(1) Test conditions are C1–C4 = 1 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 5 V and T_A = 25°C.
(3) The algebraic convention, in which the least-positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels only.
(4) Not more than one output should be shorted at a time.

Switching Characteristics(1)

V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR	Driver slew rate	R_L = 3 kΩ to 7 kΩ, See Figure 2			30	V/µs
SR(t)	Driver transition region slew rate	See Figure 3		3		V/µs
	Data rate	One TnOUT switching		120		kbit/s

(1) Test conditions are C1–C4 = 1 µF at V_{CC} = 5 V ± 0.5 V.

RECEIVER SECTION

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature range

PARAMETER			TEST CONDITIONS		MIN	TYP(2)	MAX	UNIT
V_{OH}	High-level output voltage	R1OUT, R2OUT	I_{OH} = –1 mA		3.5			V
V_{OL}	Low-level output voltage(3)	R1OUT, R2OUT	I_{OL} = 3.2 mA				0.4	V
V_{IT+}	Receiver positive-going input threshold voltage	R1IN, R2IN	V_{CC} = 5 V,	T_A = 25°C		1.7	2.4	V
$V_{IT–}$	Receiver negative-going input threshold voltage	R1IN, R2IN	V_{CC} = 5 V,	T_A = 25°C	0.8	1.2		V
V_{hys}	Input hysteresis voltage	R1IN, R2IN	V_{CC} = 5 V		0.2	0.5	1	V
r_i	Receiver input resistance	R1IN, R2IN	V_{CC} = 5 V,	T_A = 25°C	3	5	7	kΩ

(1) Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 5 V and T_A = 25°C.
(3) The algebraic convention, in which the least-positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels only.

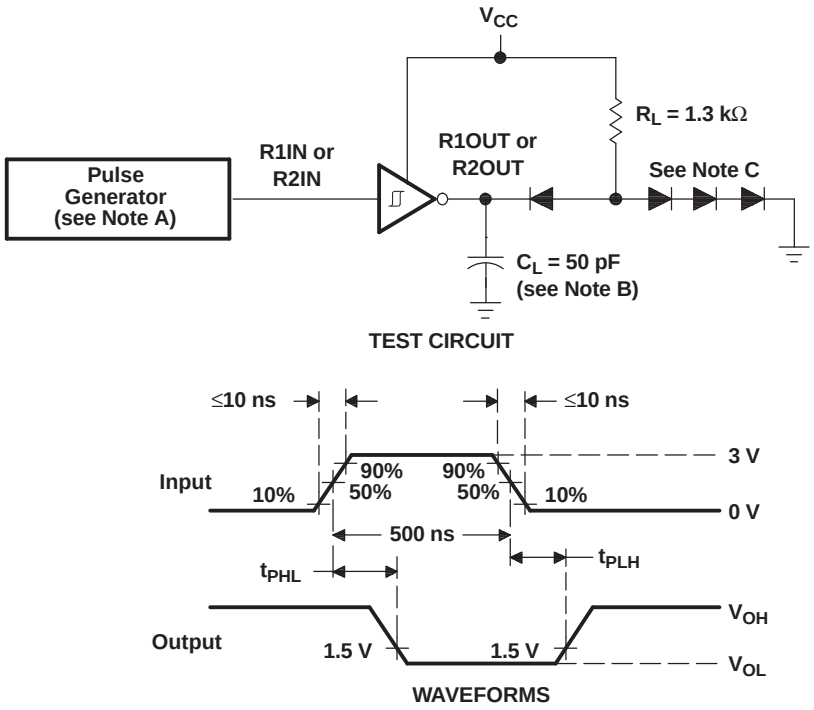
Switching Characteristics(1)

V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER		TYP	UNIT
$t_{PLH(R)}$	Receiver propagation delay time, low- to high-level output	500	ns
$t_{PHL(R)}$	Receiver propagation delay time, high- to low-level output	500	ns

(1) Test conditions are C1–C4 = 1 μF at V_{CC} = 5 V ± 0.5 V.

PARAMETER MEASUREMENT INFORMATION



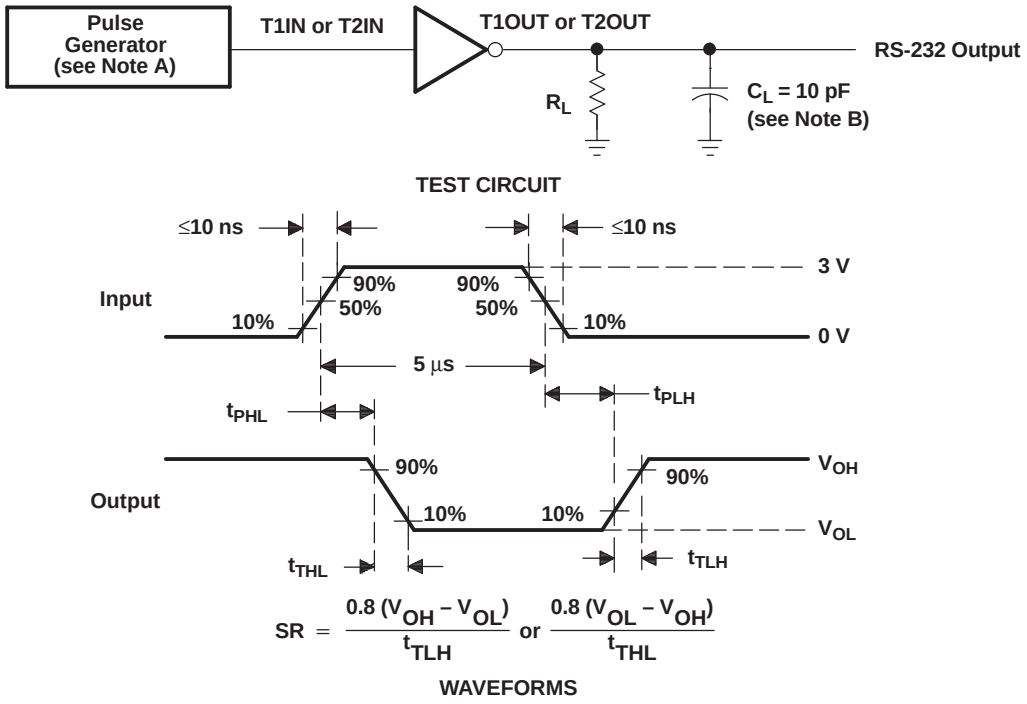
A. The pulse generator has the following characteristics: Z_O = 50 Ω, duty cycle ≤ 50%.

B. C_L includes probe and jig capacitance.

C. All diodes are 1N3064 or equivalent.

Figure 1. Receiver Test Circuit and Waveforms for t_{PHL} and t_{PLH} Measurements

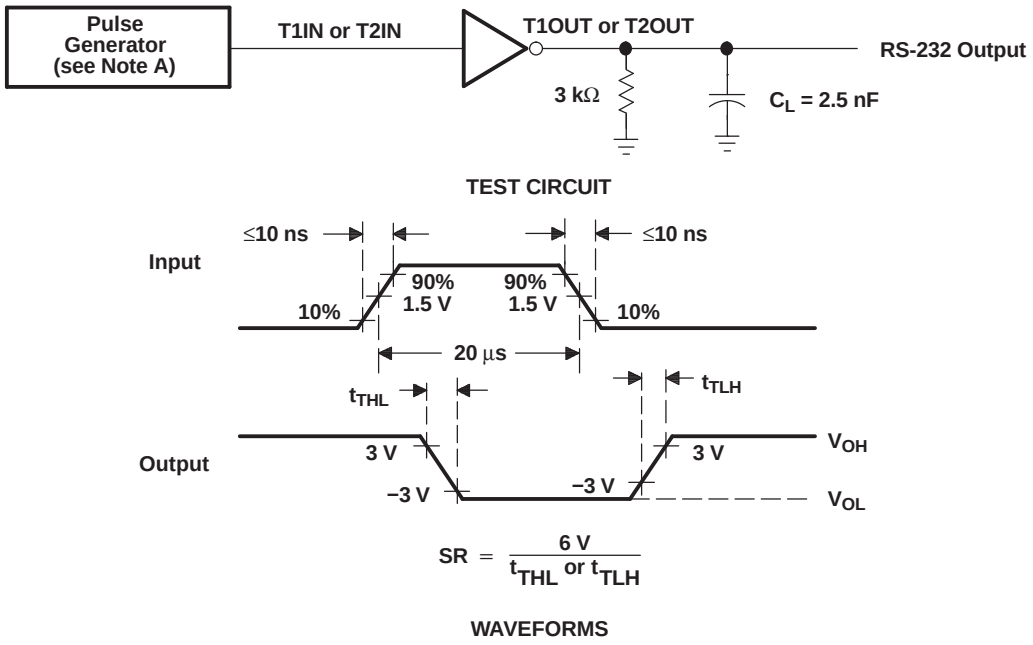
PARAMETER MEASUREMENT INFORMATION (continued)



A. The pulse generator has the following characteristics: Z_O = 50 Ω, duty cycle ≤ 50%.

B. C_L includes probe and jig capacitance.

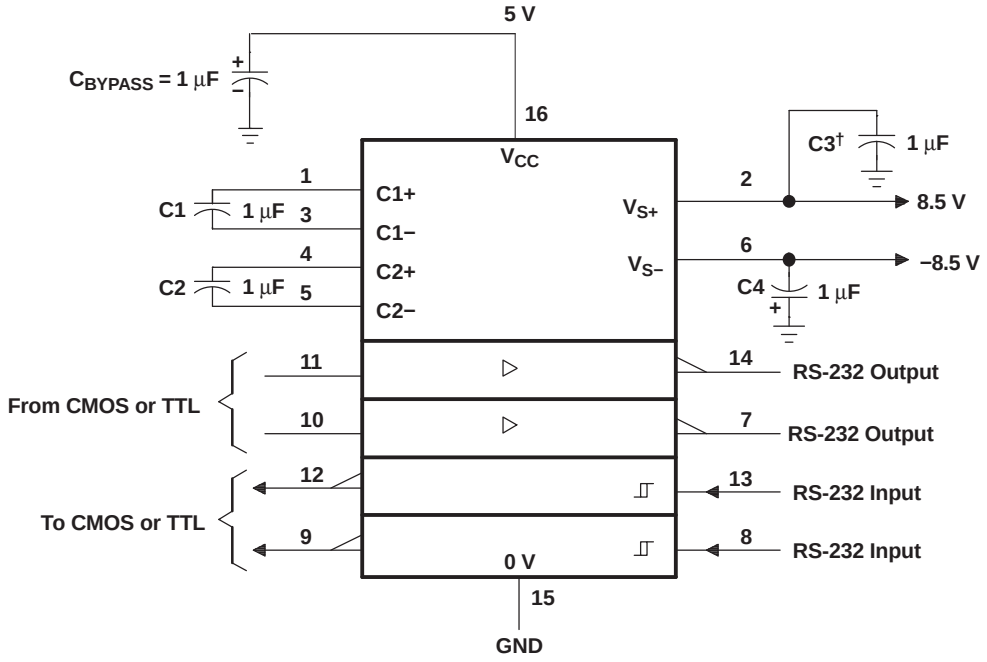
Figure 2. Driver Test Circuit and Waveforms for t_{PHL} and t_{PLH} Measurements (5-μs Input)



A. The pulse generator has the following characteristics: Z_O = 50 Ω, duty cycle ≤ 50%.

Figure 3. Test Circuit and Waveforms for t_{THL} and t_{TLH} Measurements (20-μs Input)

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown. In addition to the 1-µF capacitors shown, the TRS202 can operate with 0.1-µF capacitors.

Figure 4. Typical Operating Circuit

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TRS232D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232DWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232ID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232IDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232IDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232IDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232IDW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232IDWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232IDWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232IDWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TRS232INE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TRS232N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TRS232NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TRS232NS	ACTIVE	SO	NS	16	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232NSG4	ACTIVE	SO	NS	16	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TRS232NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

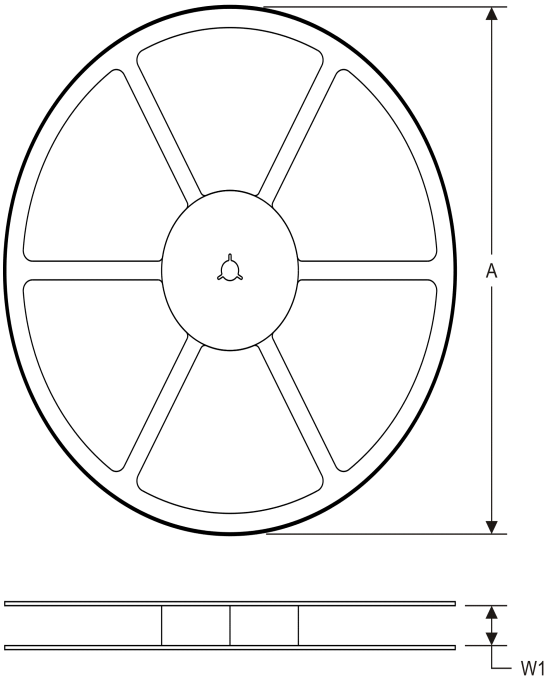
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

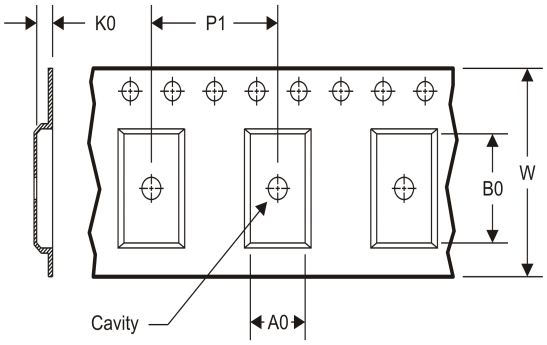
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



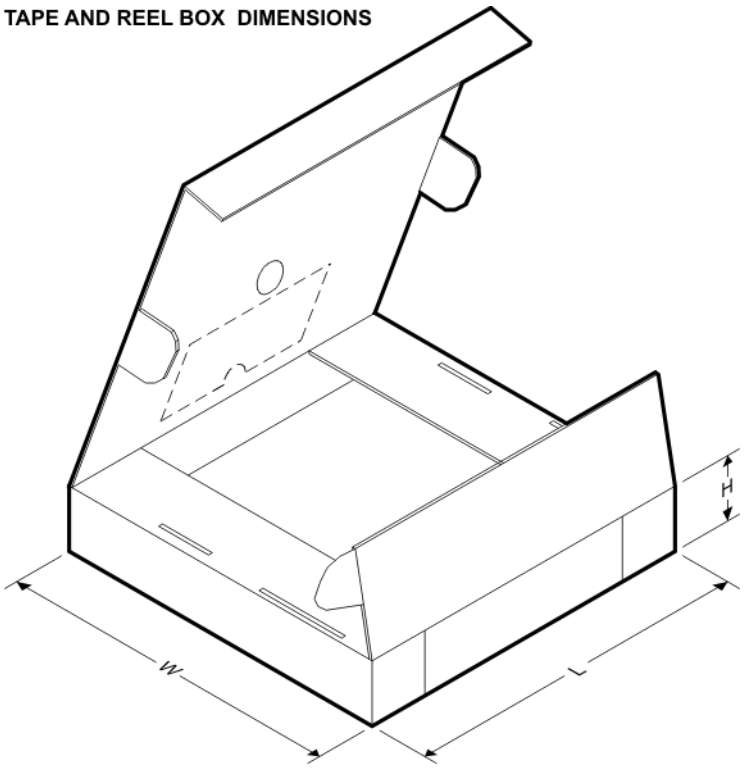
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS232DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TRS232DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
TRS232IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TRS232IDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
TRS232NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

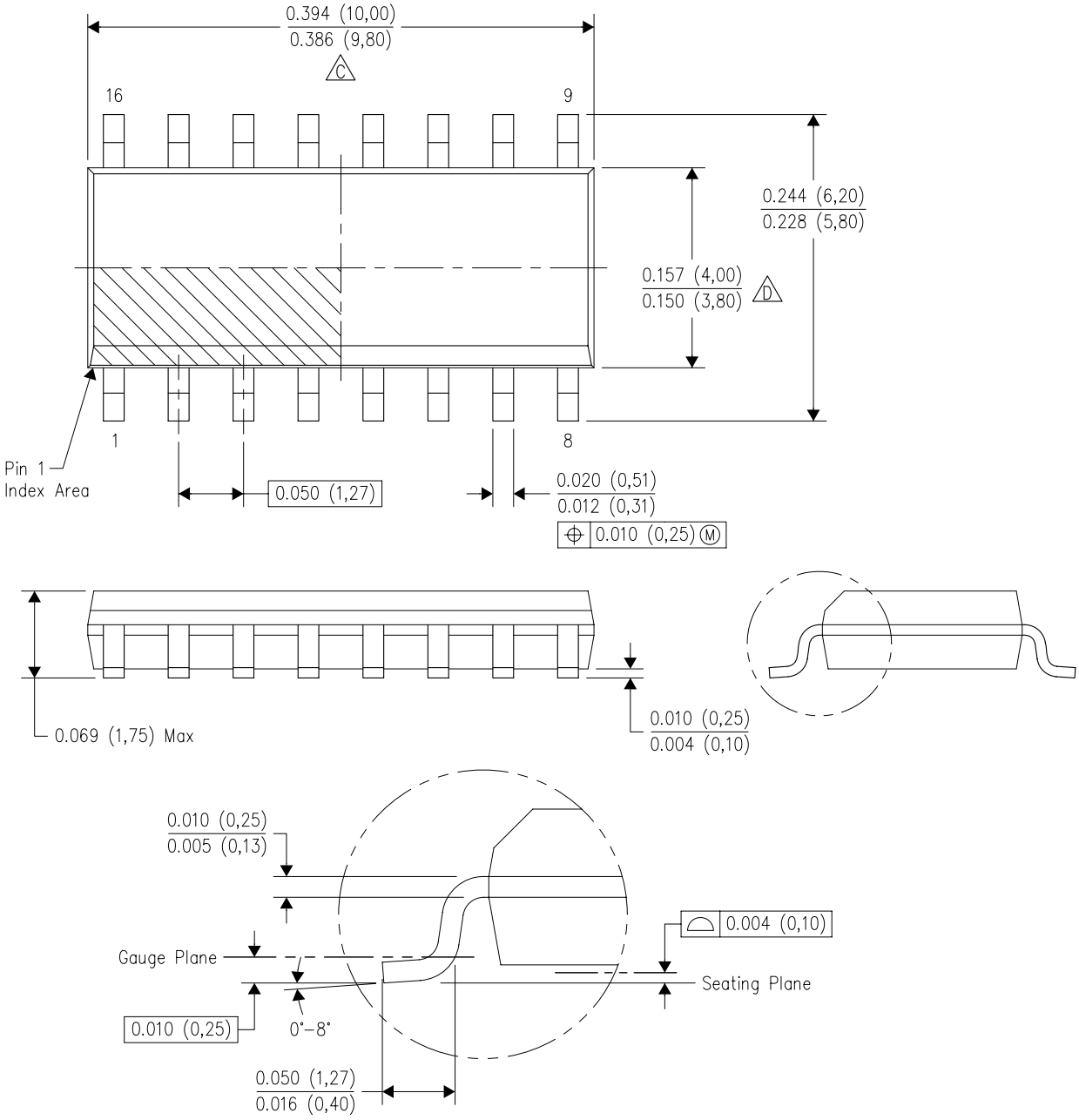
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

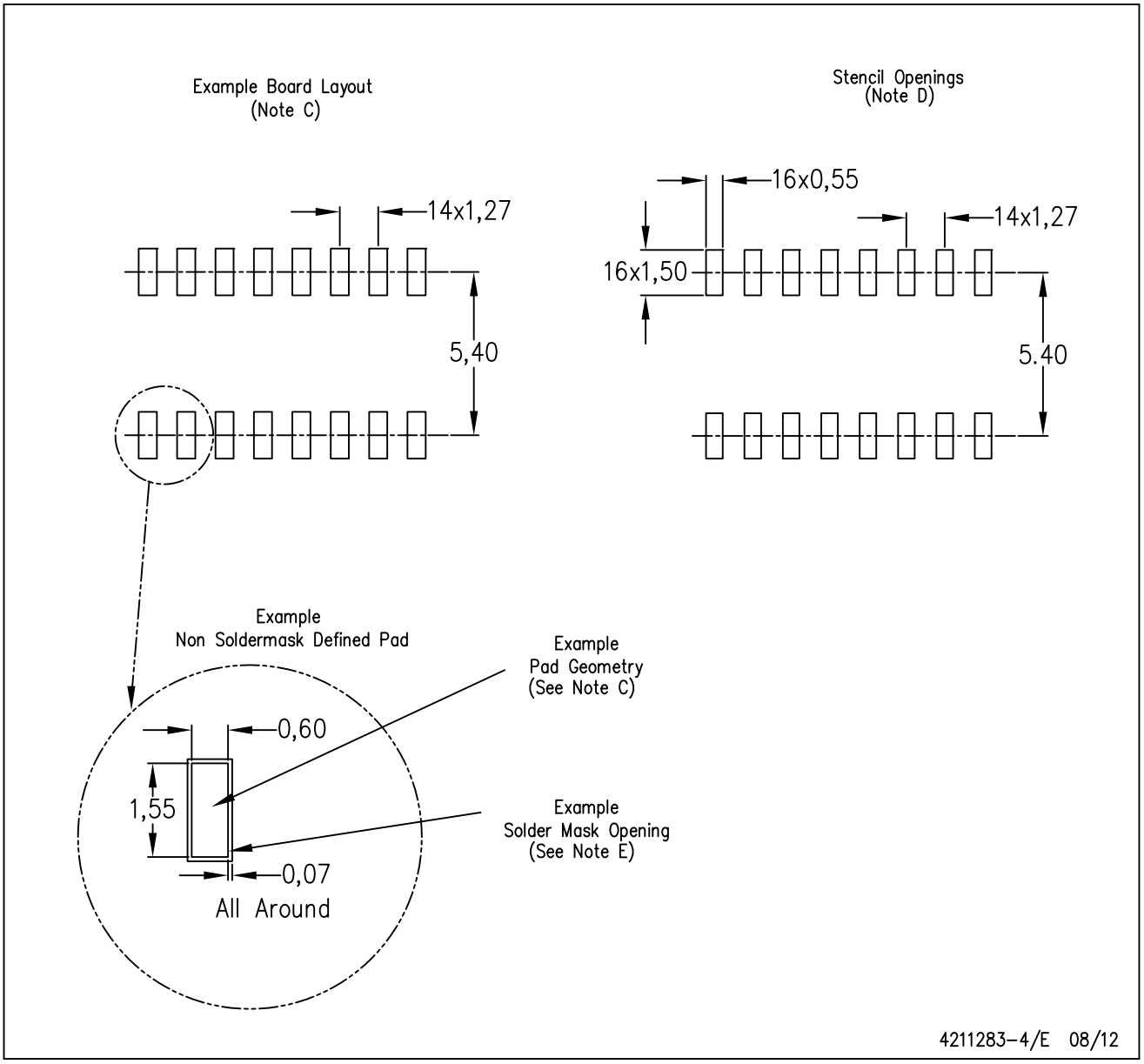
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS232DR	SOIC	D	16	2500	367.0	367.0	38.0
TRS232DWR	SOIC	DW	16	2000	367.0	367.0	38.0
TRS232IDR	SOIC	D	16	2500	333.2	345.9	28.6
TRS232IDWR	SOIC	DW	16	2000	367.0	367.0	38.0
TRS232NSR	SO	NS	16	2000	367.0	367.0	38.0

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



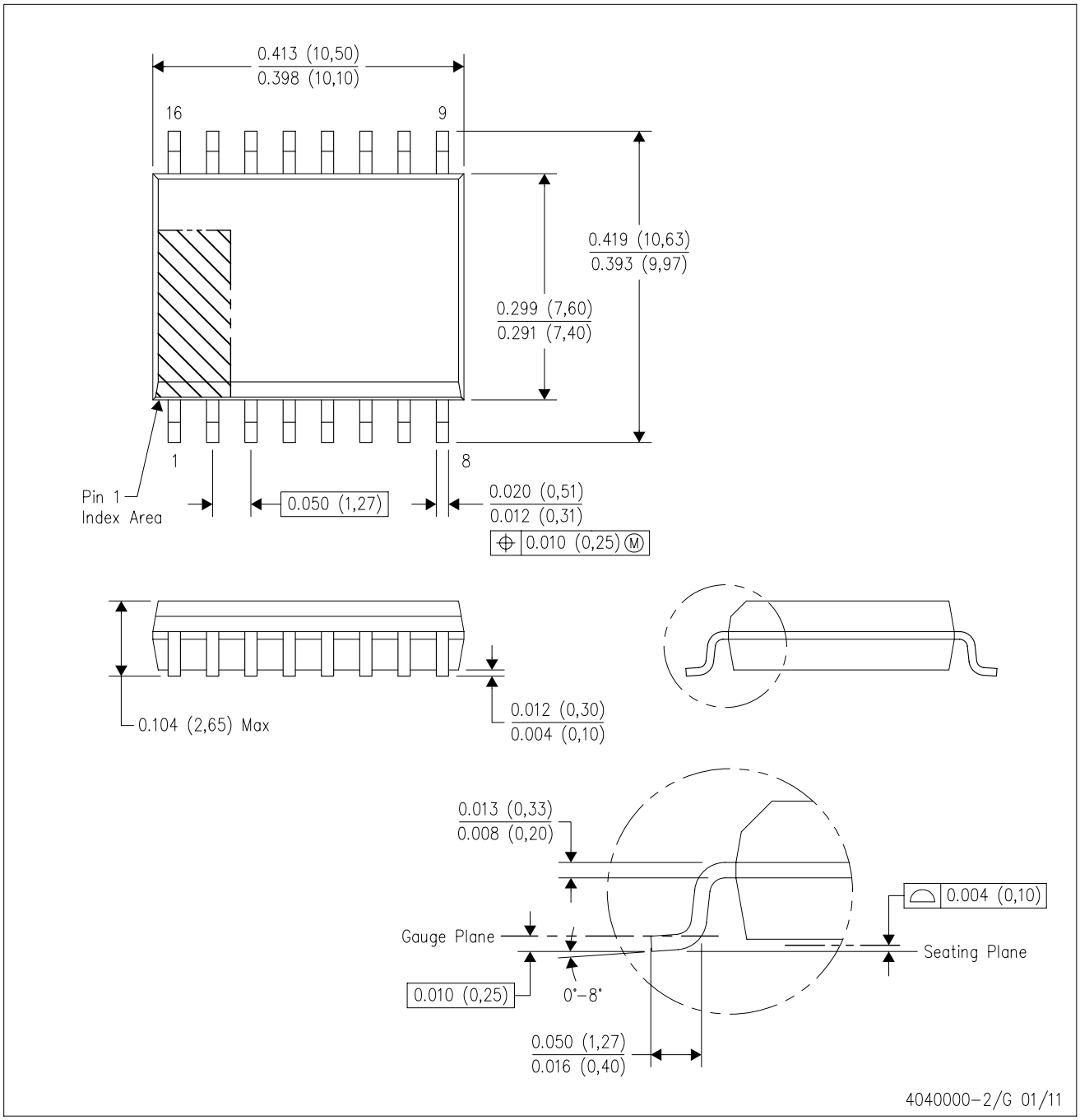
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R–PDSO–G16) PLASTIC SMALL OUTLINE

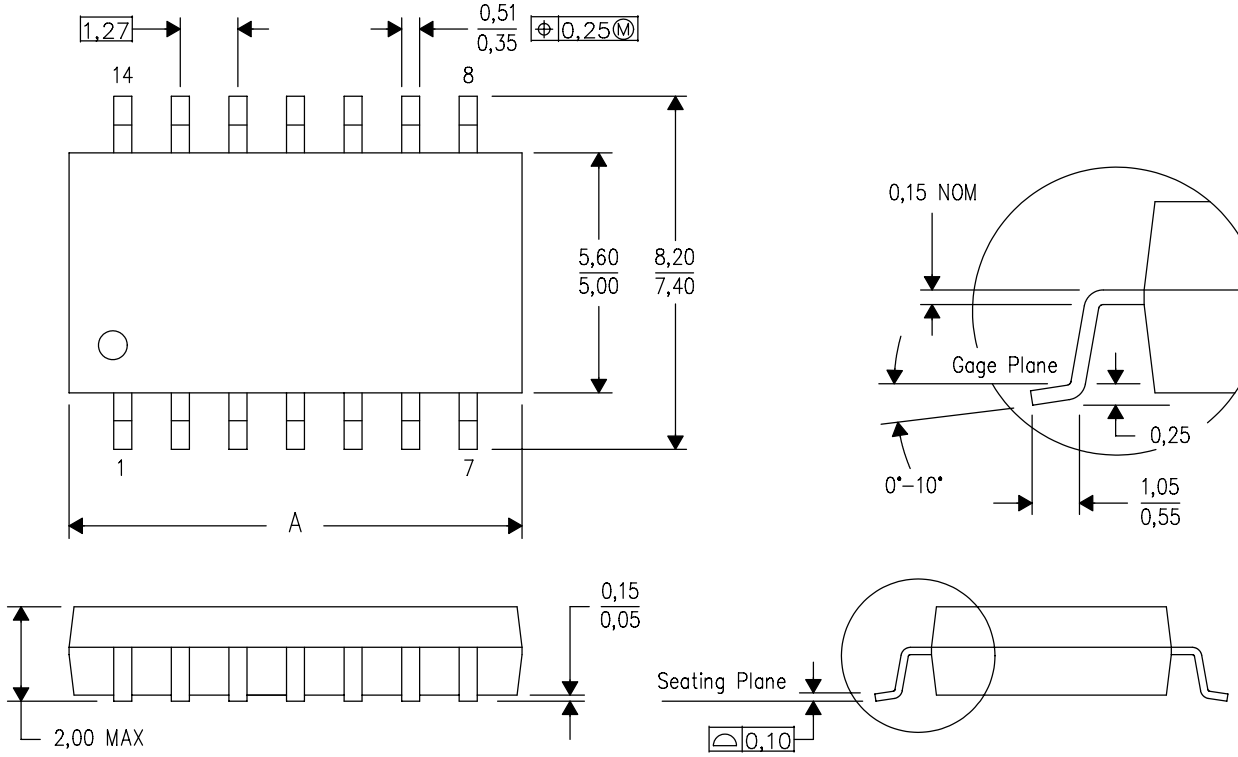


NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AA.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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